



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE #6

re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE  
FOR REFLOW SOLDERING

INFORMATION DISCLOSURE STATEMENT

**RECEIVED**

JAN 29 2002

GROUP 1700

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Pursuant to the requirements of 37 CFR §§1.56 and 1.97, the attention of the Examiner is directed to the documents listed on the attached Form PTO-1449. A copy of each of the listed documents is attached. Neither this Statement nor the listing of these documents on Form PTO-1449 is an admission that these documents are prior art as to the Applicants nor a representation that a search has been made or that no more pertinent documents exist.

The Applicants' representative certifies that the attached documents were cited in a communication from the European Patent Office in a counterpart foreign patent application not more than

three months before the filing date of this Information Disclosure Statement. A copy of the search report for the foreign patent application is also attached.

The Applicants respectfully request that the attached documents be considered by the Examiner and made of record in the referenced patent application.

Respectfully submitted,



Michael Tobias  
Registration Number 32,948

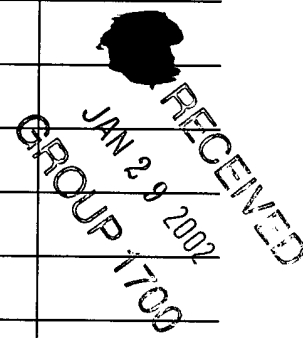
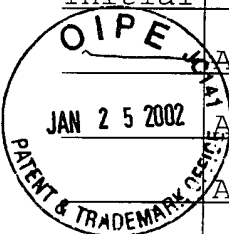
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Form PTO-1449 (Modified)

Atty Docket No.  
1023Serial No.  
09/642,765List of Patents and Publications  
For Applicant's Information  
Disclosure StatementApplicant  
TAGUCHI ET AL(Use several sheets  
if necessary)Filing Date  
August 22, 2000Group  
1725

## U.S. PATENT DOCUMENTS

Exr's Initial	Document No.	Date	Name	Class	Sub class	Filing Date
AA	5 2 2 9 0 7 0	7/20/93	Melton et al	420	557	7/2/92
AB						
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						



## FOREIGN PATENT DOCUMENTS

Document No.	Date	Country	Class	Sub class	Translation Yes No
AK 97 0 9 4 5 5	3/13/97	WO (PCT)			
AL 09 2 9 5 1 8 2	11/18/97	Japan			X Abstract
AM					
AN					
AO					

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AP	<del>Laine-Ylijoki et al, "Development and Validation of a Lead-Free Alloy for Solder Paste Applications", IEEE Transactions on Components, Packaging and Manufacturing Technology, Part C, Vol. 20, No. 3, July 1997, pages 194-198</del>
AQ	
AR	

Examiner

Date Considered

EXAMINER: Initial if reference considered, no matter whether citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.